

## Amendments to the Claims

1. (currently amended) Décor paper for laminate flooring, having a décor and comprising conductive carbon having an average particle size of less than 1000 nm, wherein the décor paper has a paper weight between 10 g/m<sup>2</sup> and 50 g/m<sup>2</sup> and is impregnated with a resin/acrylate mixture.
2. (currently amended) Décor paper according to claim 1, wherein the resin is further comprising a urea resin and/or a melamine resin and/or an acrylate resin.
3. (previously presented) Décor paper according to claim 1, further comprising abrasion-resistant particles.
4. cancelled
5. (previously presented) Décor paper according to claim 1, wherein the carbon has an average particle size of less than 500 nm.
6. cancelled
7. (previously presented) A panel for flooring, comprising a carrier board and a décor paper according to claim 1 supported by the carrier board and forming a decorative top surface of the panel.
8. (currently amended) A panel according to claim 1, further comprising abrasion-resistant particles applied on the décor paper, and wherein the décor paper has a ~~higher~~ electrical conductivity higher than any other papers used in the manufacture of the panel.
9. cancelled

10. (previously presented) A panel according to claim 1, comprising a counter-acting paper on the underside of the carrier board.

11. (previously presented) A panel according to claim 1, wherein the carrier board is made from HDF.

12. (previously presented) A panel according to claim 1, comprising coupling elements on its sides.

13. (previously presented) Décor paper according to claim 1, wherein the carbon has an average particle size of less than 1 nm.

14. (currently amended) A panel according to claim 7, wherein the carbon ~~with~~ has an average particle size of less than 500 nm.

15-17. cancelled

18. (currently amended) A panel according to claim ~~47~~ 8, wherein the abrasion-resistant particles comprise corundum particles.

19. (currently amended) A panel according to claim ~~48~~ 7, wherein the carrier board is made from HDF.